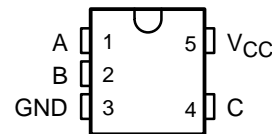


SN74AUC1G66 SINGLE BILATERAL ANALOG SWITCH

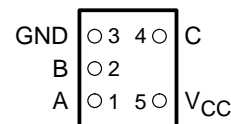
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- Available in the Texas Instruments NanoStar™ and NanoFree™ Packages
- Optimized for 1.8-V Operation and Is 3.6-V I/O Tolerant to Support Mixed-Mode Signal Operation
- Sub 1-V Operable
- Low Power Consumption, 10-μA Max I_{CC}
- High On-Off Output Voltage Ratio
- High Degree of Linearity
- High Speed – Max 0.2 ns (V_{CC} = 1.8 V, C_L = 15 pF)
- Low On-State Impedance – Typically ≈9 Ω (V_{CC} = 2.3 V)
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

DBV OR DCK PACKAGE
(TOP VIEW)



YEA OR YZA PACKAGE
(BOTTOM VIEW)



description/ordering information

This single analog switch is operational at 0.8-V to 2.7-V V_{CC}, but is designed specifically for 1.65-V to 1.95-V V_{CC} operation.

The SN74AUC1G66 can handle both analog and digital signals. It permits signals with amplitudes of up to 3.6-V (peak) to be transmitted in either direction.

NanoStar™ and NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

Applications include signal gating, chopping, modulation or demodulation (modem), and signal multiplexing for analog-to-digital and digital-to-analog conversion systems.

ORDERING INFORMATION

T _A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING‡
-40°C to 85°C	NanoStar™ WCSP (DSBGA) – YEA	Tape and reel	SN74AUC1G66YEAR	__ _U6_
	NanoFree™ WCSP (DSBGA) – YZA (Pb-free)	Tape and reel	SN74AUC1G66YZAR	
	SOT (SOT-23) – DBV	Tape and reel	SN74AUC1G66DBVR	U66_
	SOT (SC-70) – DCK	Tape and reel	SN74AUC1G66DCKR	U6_

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

‡ DBV/DCK: The actual top-side marking has one additional character that designates the assembly/test site.

YEA/YZA: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NanoStar and NanoFree are trademarks of Texas Instruments.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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SN74AUC1G66

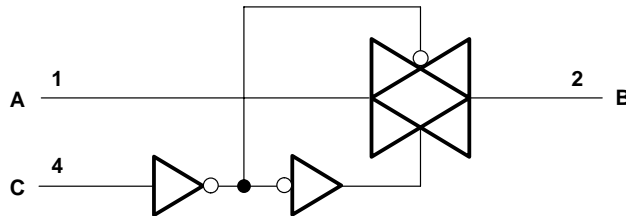
SINGLE BILATERAL ANALOG SWITCH

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FUNCTION TABLE

CONTROL INPUT (C)	SWITCH
L	OFF
H	ON

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} (see Note 1)	–0.5 V to 3.6 V
Input voltage range, V_I (see Notes 1 and 2)	–0.5 V to 3.6 V
Switch I/O voltage range, $V_{I/O}$ (see Notes 1 and 2)	–0.5 V to $V_{CC} + 0.5$ V
Control input clamp current, I_{IK} ($V_I < 0$)	–50 mA
I/O port diode current, I_{IOK} ($V_{I/O} < 0$ or $V_{I/O} > V_{CC}$)	±50 mA
On-state switch current, I_T ($V_{I/O} = 0$ to V_{CC})	±50 mA
Continuous current through V_{CC} or GND	±100 mA
Package thermal impedance, θ_{JA} (see Note 3):	
DBV package	206°C/W
DCK package	252°C/W
YEA/YZA package	154°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
- All voltages are with respect to ground unless otherwise specified.
 - The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

		MIN	MAX	UNIT
V _{CC}	Supply voltage	0.8	2.7	V
V _{IH}	High-level input voltage	V _{CC} = 0.8 V	V _{CC}	V
		V _{CC} = 1.1 V to 1.95 V	0.65 × V _{CC}	
		V _{CC} = 2.3 V to 2.7 V	1.7	
V _{IL}	Low-level input voltage	V _{CC} = 0.8 V	0	V
		V _{CC} = 1.1 V to 1.95 V	0.35 × V _{CC}	
		V _{CC} = 2.3 V to 2.7 V	0.7	
V _{I/O}	I/O port voltage	0	V _{CC}	V
V _I	Control input voltage	0	3.6	V
Δt/Δv	Input transition rise or fall rate		20	ns/V
T _A	Operating free-air temperature	−40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN TYP† MAX			UNIT
			MIN	TYP†	MAX	
r _{on}	V _I = V _{CC} or GND, V _C = V _{IH} (see Figure 1)	I _S = 4 mA	1.65 V	10	20	Ω
			I _S = 8 mA	2.3 V	9	
r _{on(p)}	V _I = V _{CC} to GND, V _C = V _{IH} (see Figure 1)	I _S = 4 mA	1.65 V	32	80	Ω
			I _S = 8 mA	2.3 V	15	
I _{S(off)}	V _I = V _{CC} and V _O = GND, or V _I = GND and V _O = V _{CC} , V _C = V _{IL} (see Figure 2)	2.7 V		±1	±0.1†	μA
I _{S(on)}	V _I = V _{CC} or GND, V _C = V _{IH} , V _O = Open (see Figure 3)	2.7 V		±1	±0.1†	μA
I _I	V _I = V _{CC} or GND	0 to 2.7 V			±5	μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	0.8 V to 2.7 V			10	μA
C _{IC}		2.5 V		2		pF
C _{io(off)}		2.5 V		3.5		pF
C _{io(on)}		2.5 V		7		pF

† All typical values are at T_A = 25°C.

switching characteristics over recommended operating free-air temperature range, C_L = 15 pF (unless otherwise noted) (see Figure 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 0.8 V	V _{CC} = 1.2 V ± 0.1 V		V _{CC} = 1.5 V ± 0.1 V		V _{CC} = 1.8 V ± 0.15 V			V _{CC} = 2.5 V ± 0.2 V		UNIT
			TYP	MIN	MAX	MIN	MAX	MIN	TYP	MAX	MIN	MAX	
t _{pd} ‡	A or B	B or A	0.9		0.3		0.2		0.2		0.1		ns
t _{en}	C	A or B	4.1	0.5	2.6	0.5	1.7	0.5	0.8	1.1	0.5	1	ns
t _{dis}	C	A or B	5	0.7	3.6	0.5	2.6	0.5	1.7	2.9	0.5	2.2	ns

‡ The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

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switching characteristics over recommended operating free-air temperature range, $C_L = 30 \text{ pF}$ (unless otherwise noted) (see Figure 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$			$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$		UNIT
			MIN	TYP	MAX	MIN	MAX	
t_{pd}^\dagger	A or B	B or A			0.3		0.3	ns
t_{en}	C	A or B	0.5	1.4	2.3	0.8	1.4	ns
t_{dis}	C	A or B	0.5	1.7	2.9	0.5	1.5	ns

† The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).



analog switch characteristics, $T_A = 25^\circ\text{C}$

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	V _{CC}	TYP	UNIT
Frequency response [†] (switch ON)	A or B	B or A	$C_L = 50\text{ pF}$, $R_L = 600\ \Omega$, $f_{in} = \text{sine wave}$ (see Figure 5)	0.8 V	60	MHz
				1.1 V	60	
				1.4 V	80	
				1.65 V	120	
				2.3 V	170	
			$C_L = 5\text{ pF}$, $R_L = 50\ \Omega$, $f_{in} = \text{sine wave}$ (see Figure 5)	0.8 V	>500	
				1.1 V	>500	
				1.4 V	>500	
				1.65 V	>500	
				2.3 V	>500	
Crosstalk (control input to signal output)	C	A or B	$C_L = 50\text{ pF}$, $R_L = 600\ \Omega$, $f_{in} = 1\text{ MHz}$ (square wave) (see Figure 6)	0.8 V	9	mV
				1.1 V	14	
				1.4 V	15	
				1.65 V	16	
				2.3 V	20	
Feed-through attenuation [‡] (switch OFF)	A or B	B or A	$C_L = 50\text{ pF}$, $R_L = 600\ \Omega$, $f_{in} = 1\text{ MHz}$ (sine wave) (see Figure 7)	0.8 V	-60	dB
				1.1 V	-60	
				1.4 V	-60	
				1.65 V	-60	
				2.3 V	-60	
			$C_L = 5\text{ pF}$, $R_L = 50\ \Omega$, $f_{in} = 1\text{ MHz}$ (sine wave) (see Figure 7)	0.8 V	-55	
				1.1 V	-55	
				1.4 V	-55	
				1.65 V	-55	
				2.3 V	-55	
Sine-wave distortion	A or B	B or A	$C_L = 50\text{ pF}$, $R_L = 10\text{ k}\Omega$, $f_{in} = 1\text{ kHz}$ (sine wave) (see Figure 8)	0.8 V	7.5	%
				1.1 V	0.16	
				1.4 V	0.04	
				1.65 V	0.03	
				2.3 V	0.02	
	A or B	B or A	$C_L = 50\text{ pF}$, $R_L = 10\text{ k}\Omega$, $f_{in} = 10\text{ kHz}$ (sine wave) (see Figure 8)	0.8 V	4.2	
				1.1 V	0.2	
				1.4 V	0.03	
				1.65 V	0.02	
				2.3 V	0.02	

[†] Adjust f_{in} voltage to obtain 0 dBm at output. Increase f_{in} frequency until dB meter reads -3 dB.

[‡] Adjust f_{in} voltage to obtain 0 dBm at input.

operating characteristics, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	V _{CC} = 0.8 V	V _{CC} = 1.2 V	V _{CC} = 1.5 V	V _{CC} = 1.8 V	V _{CC} = 2.5 V	UNIT
		TYP	TYP	TYP	TYP	TYP	
C _{pd} Power dissipation capacitance	f = 10 MHz	3	3	3	3	3	pF

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PARAMETER MEASUREMENT INFORMATION

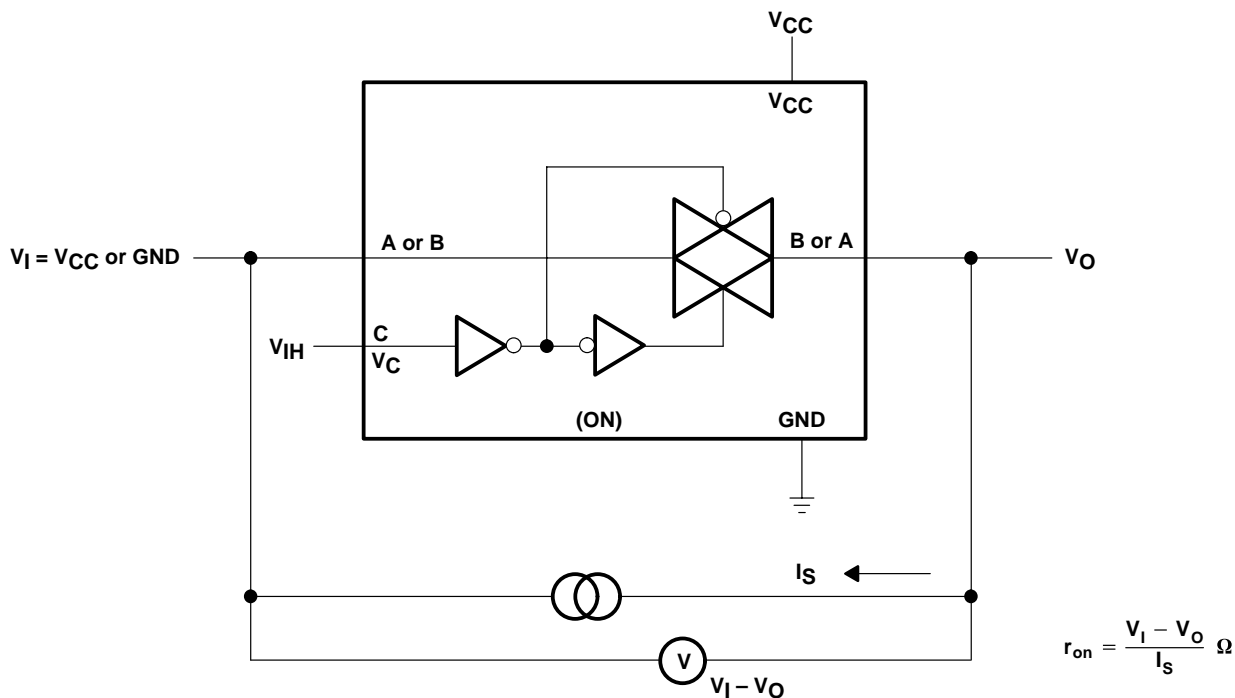


Figure 1. On-State Resistance Test Circuit

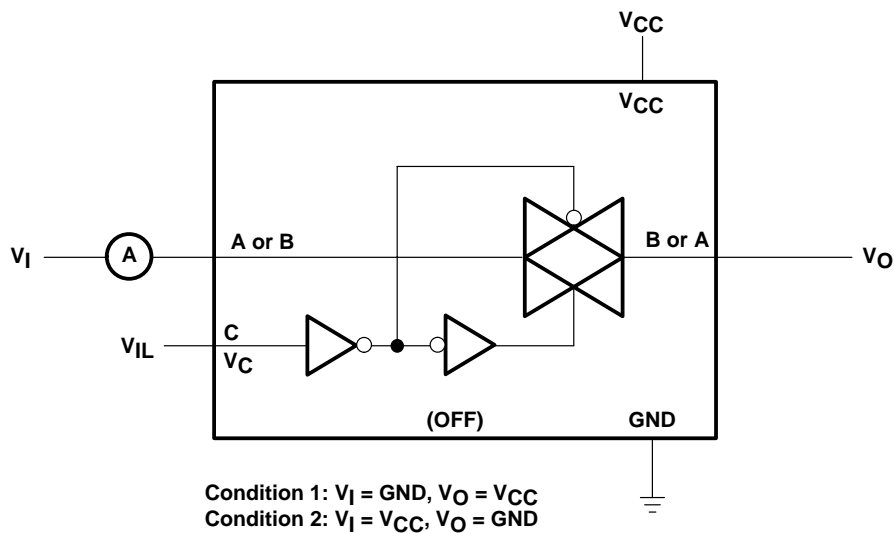


Figure 2. Off-State Switch Leakage-Current Test Circuit

PARAMETER MEASUREMENT INFORMATION

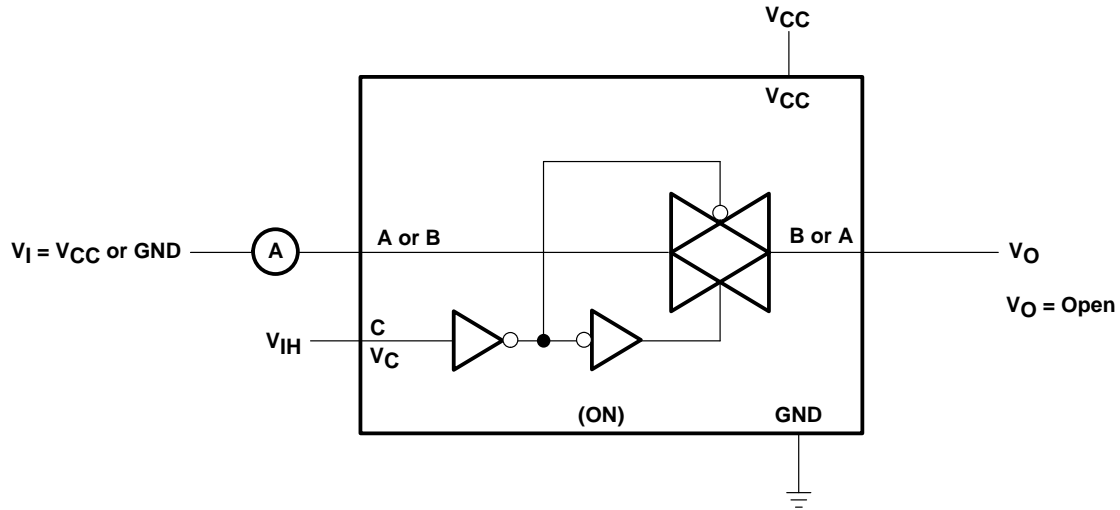
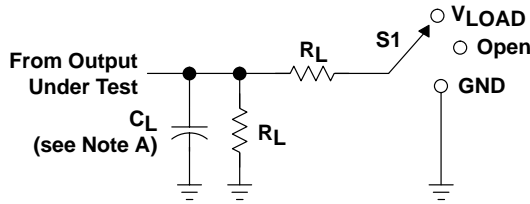


Figure 3. On-State Leakage-Current Test Circuit

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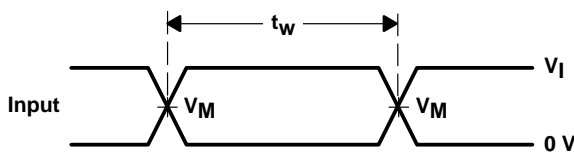
PARAMETER MEASUREMENT INFORMATION



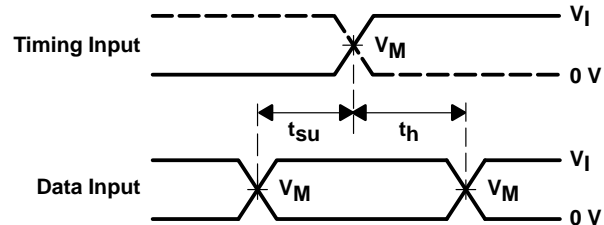
TEST	S1
tPLH/tPHL	Open
tPLZ/tPZL	VLOAD
tPHZ/tPZH	GND

LOAD CIRCUIT

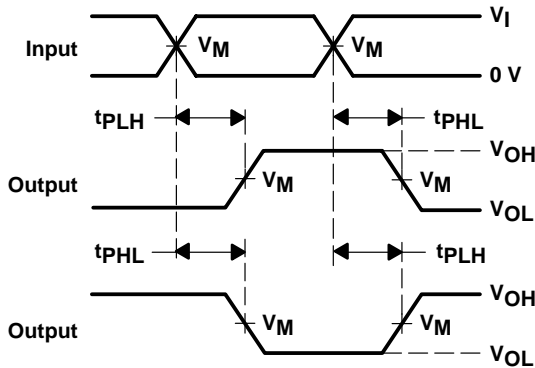
VCC	INPUTS		VM	VLOAD	CL	RL	VΔ
	VI	tr/tf					
0.8 V	VCC	≤2 ns	VCC/2	2 × VCC	15 pF	2 kΩ	0.1 V
1.2 V ± 0.1 V	VCC	≤2 ns	VCC/2	2 × VCC	15 pF	2 kΩ	0.1 V
1.5 V ± 0.1 V	VCC	≤2 ns	VCC/2	2 × VCC	15 pF	2 kΩ	0.1 V
1.8 V ± 0.15 V	VCC	≤2 ns	VCC/2	2 × VCC	15 pF	2 kΩ	0.15 V
2.5 V ± 0.2 V	VCC	≤2 ns	VCC/2	2 × VCC	15 pF	2 kΩ	0.15 V
1.8 V ± 0.15 V	VCC	≤2 ns	VCC/2	2 × VCC	30 pF	1 kΩ	0.15 V
2.5 V ± 0.2 V	VCC	≤2 ns	VCC/2	2 × VCC	30 pF	500 Ω	0.15 V



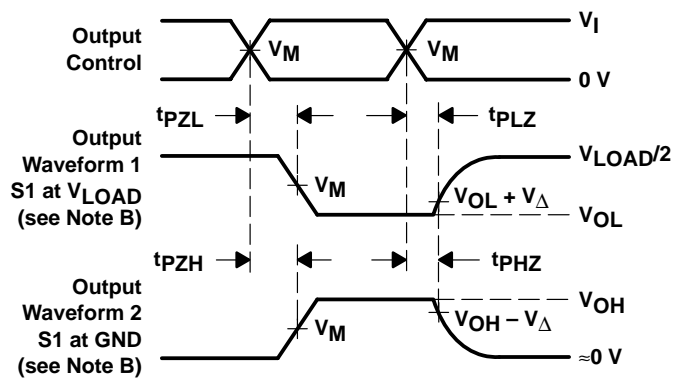
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. CL includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, ZO = 50 Ω, slew rate ≥ 1 V/ns.
 D. The outputs are measured one at a time with one transition per measurement.
 E. tPLZ and tPHZ are the same as tdis.
 F. tPZL and tPZH are the same as ten.
 G. tPLH and tPHL are the same as tpd.
 H. All parameters and waveforms are not applicable to all devices.

Figure 4. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION

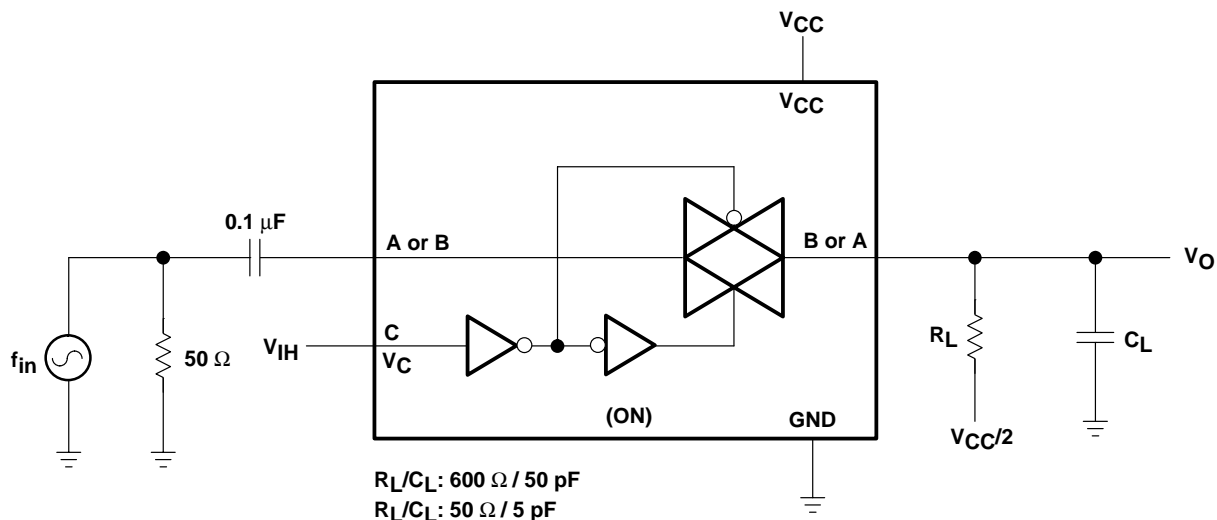


Figure 5. Frequency Response (Switch ON)

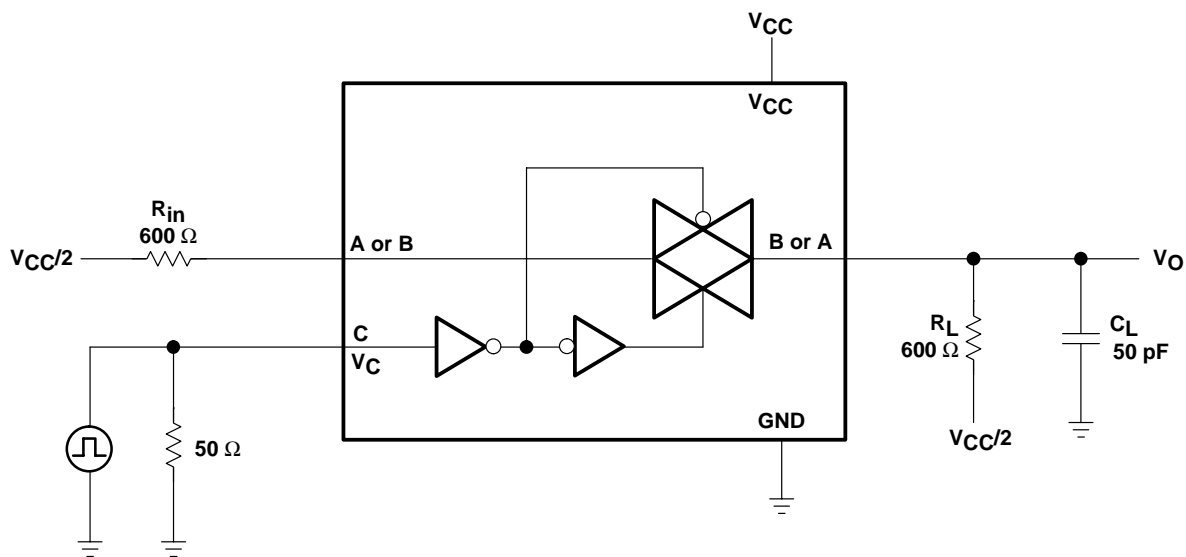


Figure 6. Crosstalk (Control Input – Switch Output)

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PARAMETER MEASUREMENT INFORMATION

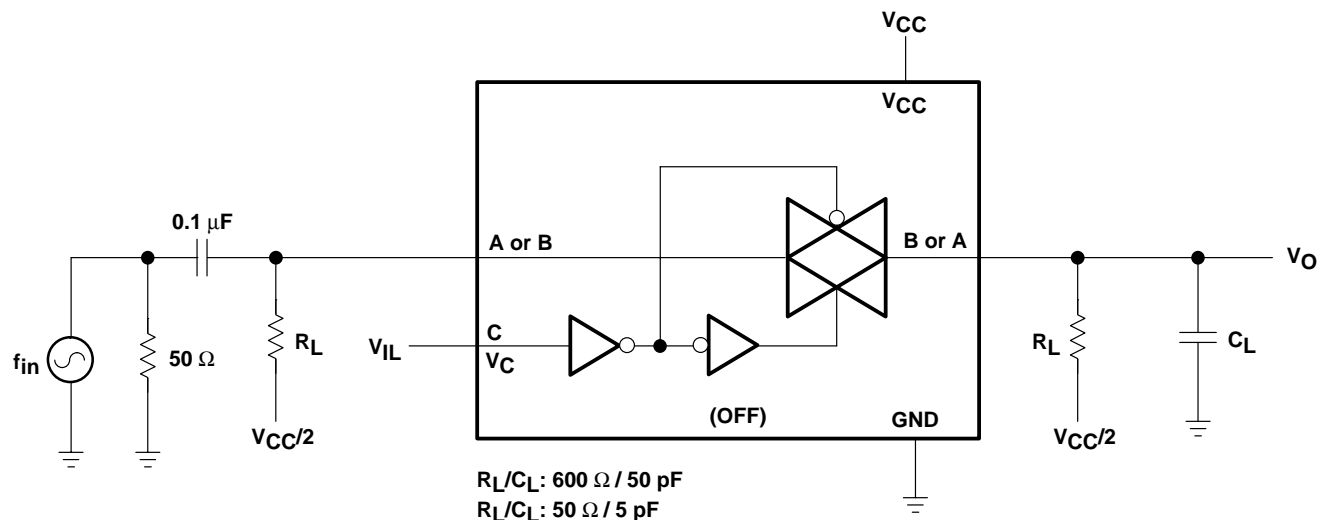


Figure 7. Feed Through, Switch Off

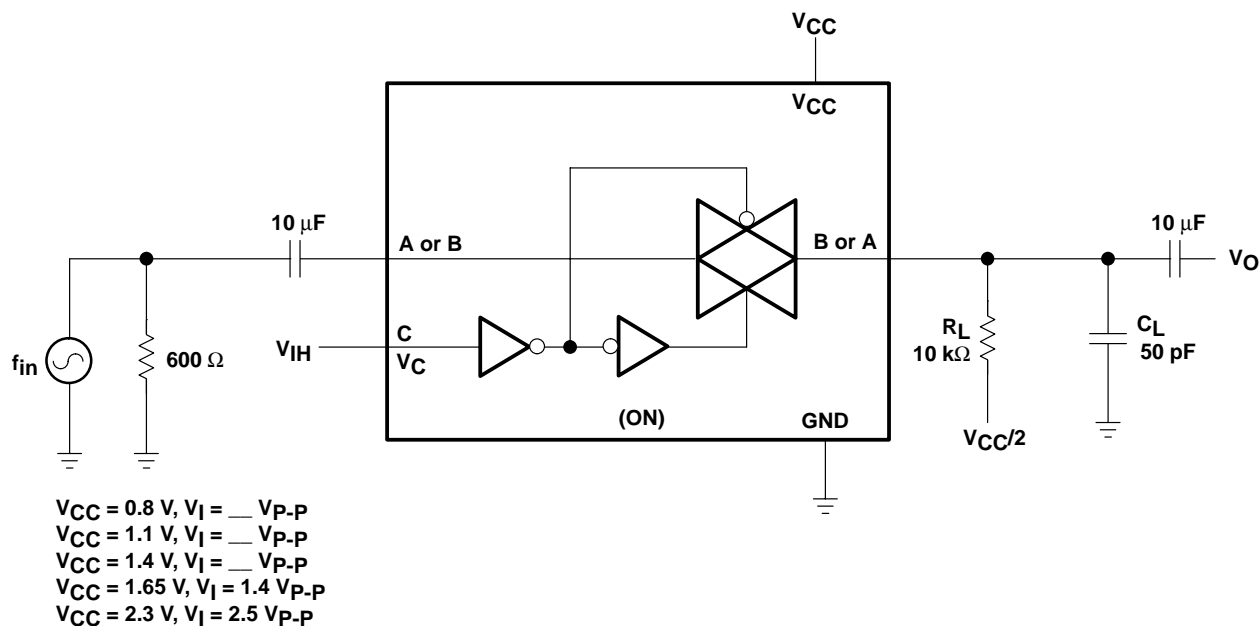


Figure 8. Sine-Wave Distortion

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74AUC1G66DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUC1G66DCKR	ACTIVE	SC70	DCK	5	3000	Pb-Free (RoHS)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUC1G66YEAR	ACTIVE	WCSP	YEA	5	3000	None	SNPB	Level-1-260C-UNLIM
SN74AUC1G66YZAR	ACTIVE	WCSP	YZA	5	3000	None	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - May not be currently available - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

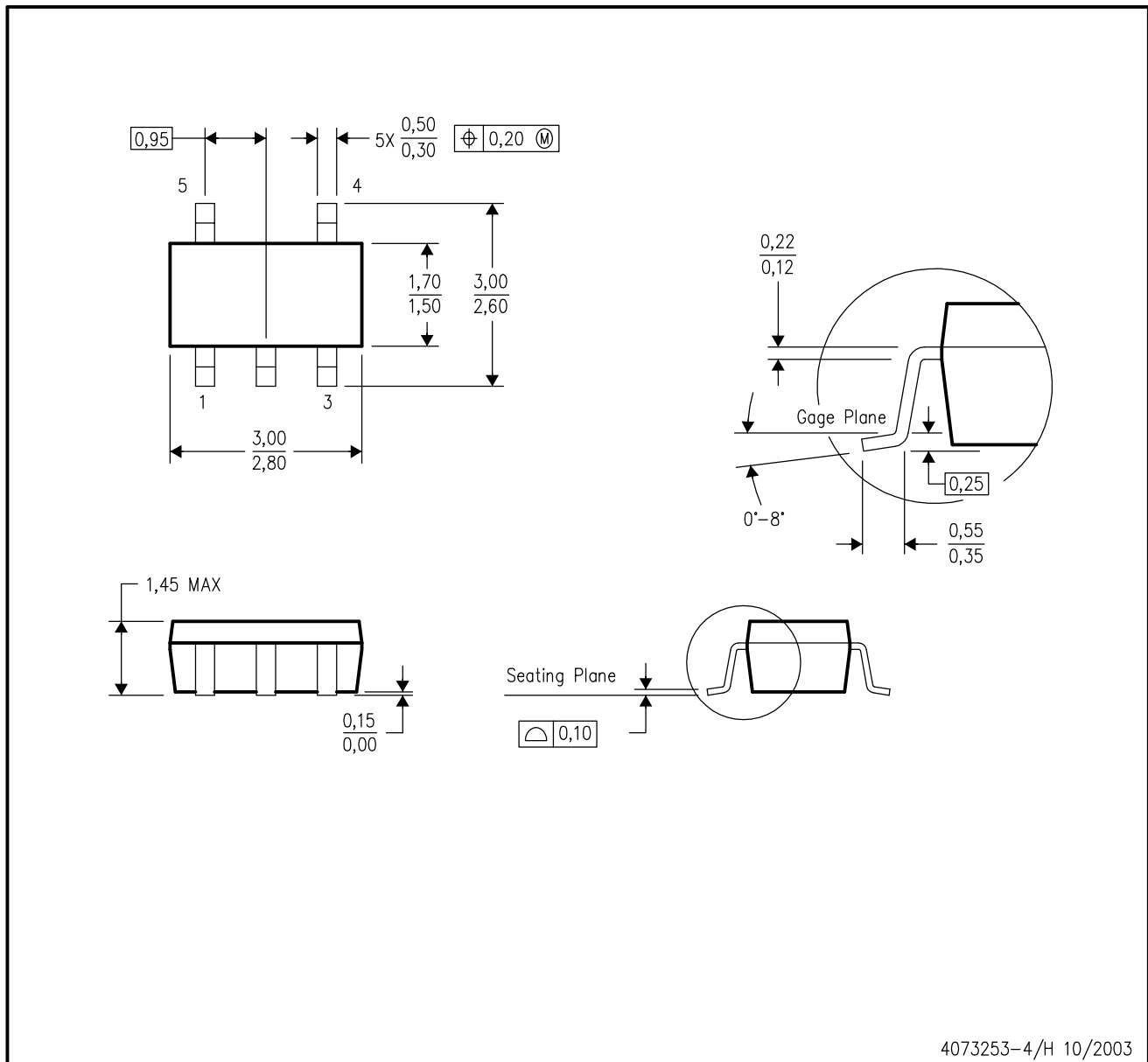
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DBV (R-PDSO-G5)

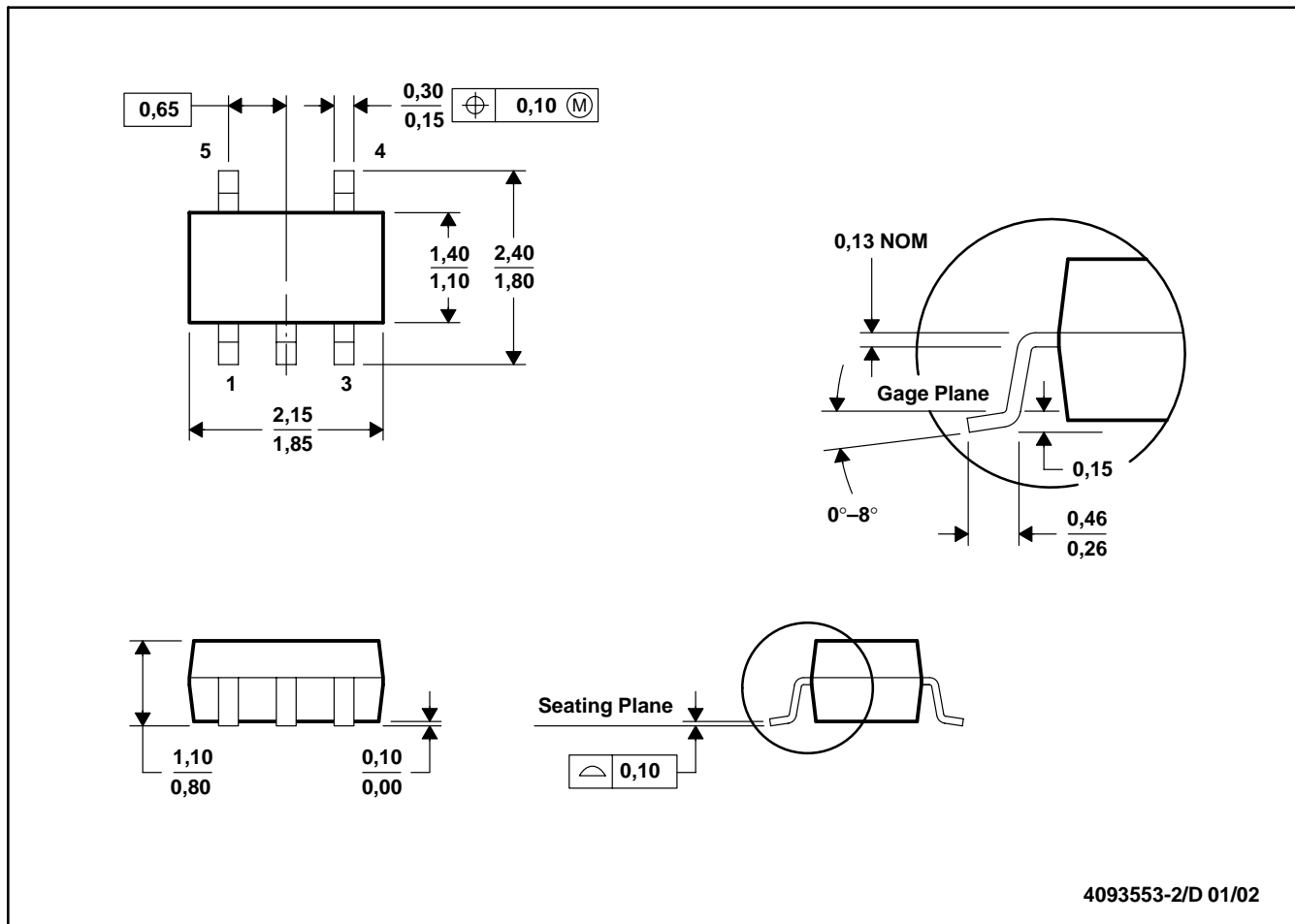
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion.
 - D. Falls within JEDEC MO-178 Variation AA.

DCK (R-PDSO-G5)

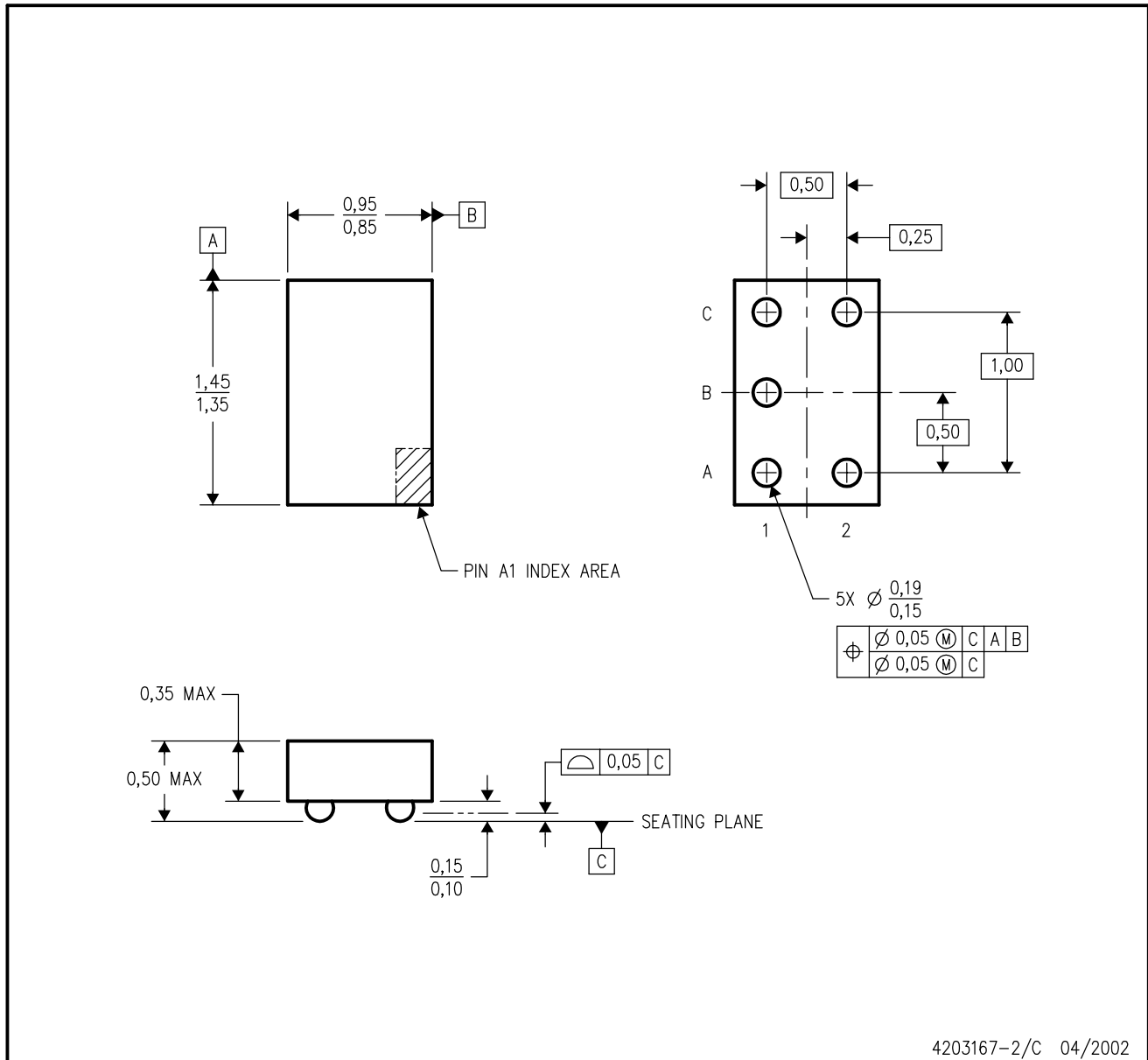
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion.
 D. Falls within JEDEC MO-203

YEA (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY

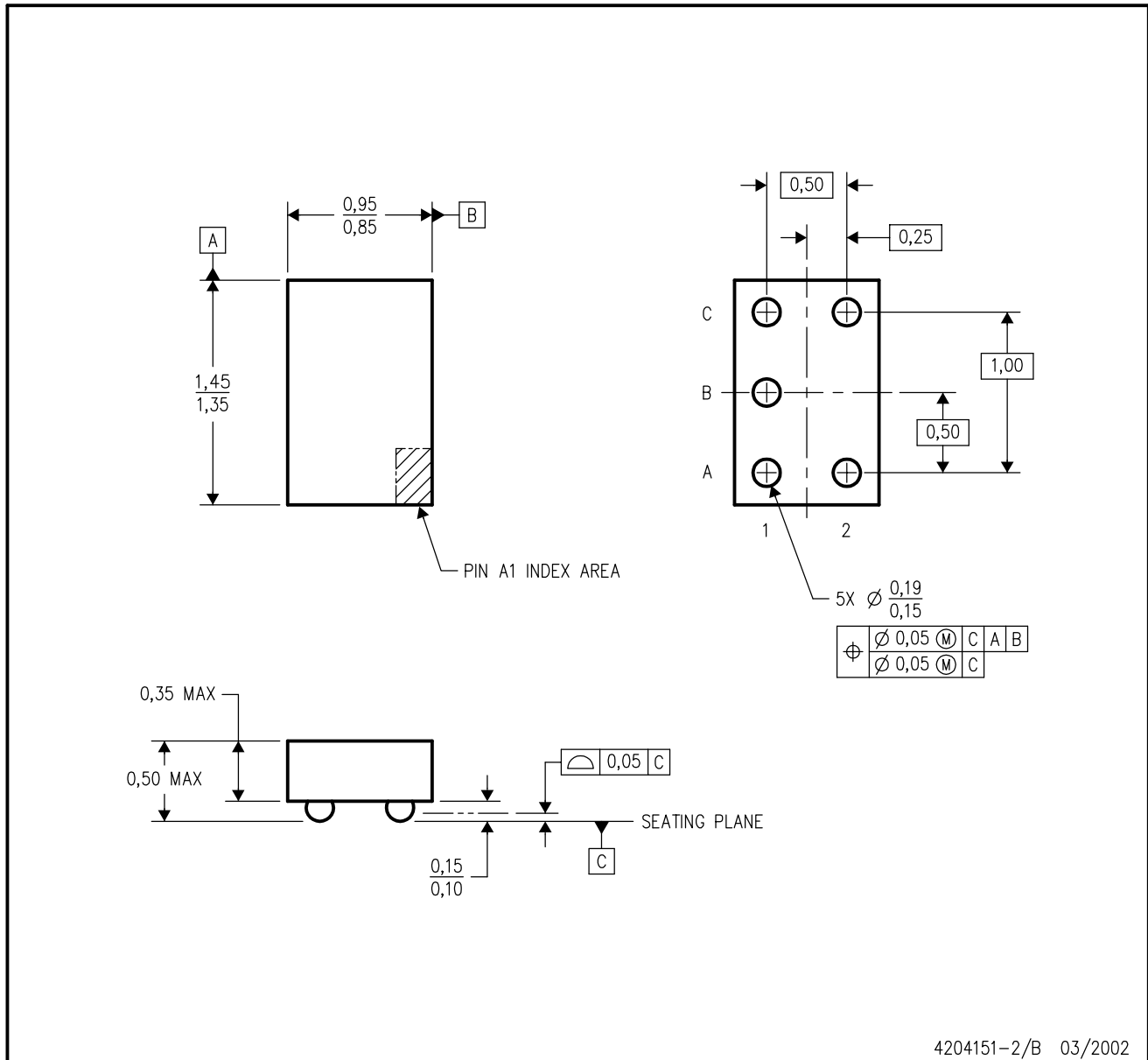


- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. NanoStar™ package configuration.
 - D. Package complies to JEDEC MO-211 variation EA.
 - E. This package is tin-lead (SnPb). Refer to the 5 YZA package (drawing 4204151) for lead-free.

NanoStar is a trademark of Texas Instruments.

YZA (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. NanoFree™ package configuration.
 - D. Package complies to JEDEC MO-211 variation EA.
 - E. This package is lead-free. Refer to the 5 YEA package (drawing 4203167) for tin-lead (SnPb).

NanoFree is a trademark of Texas Instruments.

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